

Method and apparatus for conditioning a polishing pad used in chemical mechanical planarization

Publication number: TW436374B

Publication date: 2001-05-28

Inventor: LABUNSKY MICHAEL (US); HUYNH TAC (US); MEYER ANTHONY S (US); NAGENGAST ANDREW J (US); TRAVIS GLENN W (US)

Applicant: LAM RES CORP (US)

Classification:

- International: *B24B53/00; B24B37/00; B24B37/04; B24B49/16; B24B53/007; B24B53/02; B24B53/12; B24B55/06; B24D5/02; H01L21/304; B24B53/00; B24B37/00; B24B37/04; B24B49/16; B24B53/007; B24B53/12; B24B55/00; B24D5/00; H01L21/02; (IPC1-7): B24B7/24; B24B37/04; H01L21/304*

- European: B24B37/04I; B24B49/16; B24B53/007; B24D5/02

Application number: TW19990119569 20000124

Priority number(s): US19980188779 19981109

Also published as:



WO0027585 (A1)

EP1128932 (A1)

US6328637 (B1)

US6086460 (A1)

EP1128932 (A0)

Report a data error here

Abstract of TW436374B

A method and apparatus for conditioning a polishing pad is described. The method includes steps of moving a cylindrical roller having an abrasive substance affixed to it against a moving polishing pad. The roller may be passively rotated by contact with the polishing pad, or actively reciprocated, while maintaining a pressure against the polishing pad. The apparatus includes a cylindrical roller attached to one or more pressure application devices mechanically connected to the roller.

Data supplied from the **esp@cenet** database - Worldwide